

Chip Scale[®]

ChipScaleReview.com R E V I E W



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2014
MEDIA KIT

CHIP SCALE REVIEW

Expanding your Reach. Connect. Deliver.

Chip Scale Review expands your reach, connects with leading industry contacts, delivers your company message. Plan now for your company's advertising campaign in 2014.

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Chip Scale Review Sets the Standard for Semiconductor Packaging Publications

Founded in 1997, **Chip Scale Review** is the leading international publication serving the semiconductor packaging industry today, bringing you the most up-to-date technology advancements in both contemporary and advanced assembly, test, and packaging processes and technologies for ICs, MEMS, RF/Wireless, optoelectronic, and emerging areas such as nanotechnology and LED packaging. From cover to cover, **Chip Scale Review** is packed with technology features, market trends, industry news, industry events, expert perspective, and international directories that can't be found elsewhere.



Chip Scale Review is the first word in middle-end and back-end technologies for advanced semiconductors. Whether it's TSV and associated processes, wafer-level packaging, semiconductor packaging and final test advances – CSR showcases the industry leaders with exclusive editorial content.

AUDIENCE DEMOGRAPHICS

The Chip Scale Review brand encompasses the flagship publication now entering its 17th year which is published six times per year in print and digital. The monthly technical newsletter **CSR Tech Monthly** is an extension of the publication and is produced 12x per year on the third Tuesday of every month.

Chip Scale Review audience comprises 24,000 subscribers that consist of test & assembly packaging engineers, engineering management, general and corporate management at OEMs, device manufacturers, contract manufacturers and IC Packaging Foundries plus R&D research institutes, educational institutions, and government who are involved in the advanced packaging industry.

JOB FUNCTION

CORPORATE & GENERAL MANAGEMENT:



ENGINEERING MANAGEMENT:



ASSEMBLY PACKAGING ENGINEER:



R&D:



TEST ENGINEERING



IC DESIGN ENGINEER:



RELIABILITY QA:



PURCHASING:



OTHER:



UNIVERSITY, INSTITUTES, STUDENTS – OTHER:



DISTRIBUTION

PRINT: 14,250

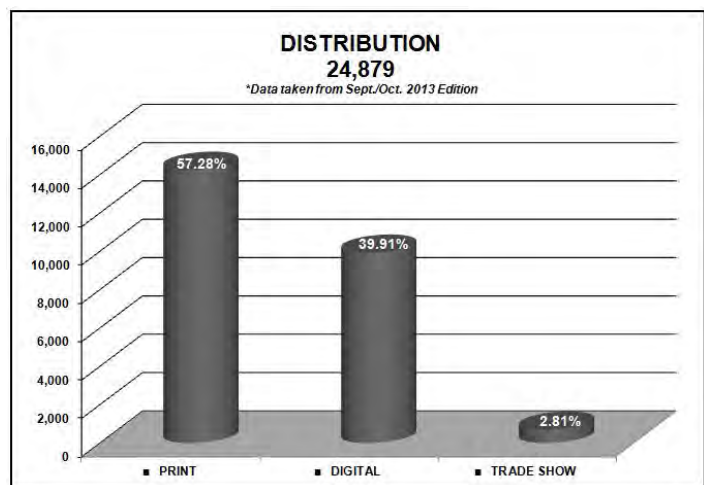
DIGITAL: 9,929

TRADE SHOW: 700

TOTAL

DISTRIBUTION*: 24,879

*Data taken from Sept./Oct. 2013 Edition



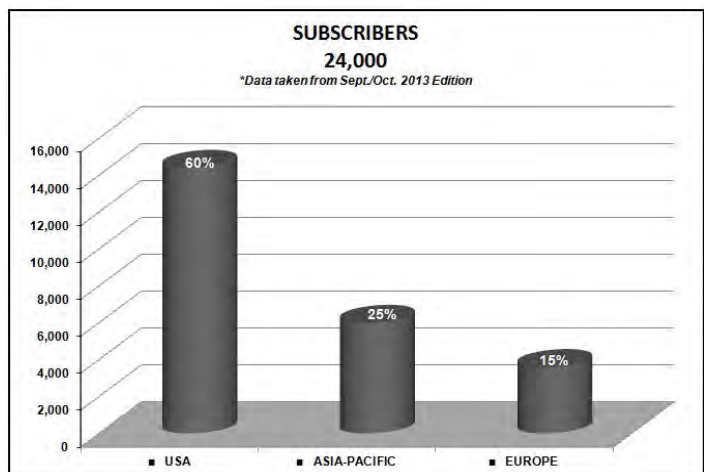
SUBSCRIBERS

USA: 14,400

ASIA-PACIFIC: 6,000

EUROPE: 3,600

Data Sources based on print run, shipping receipts, and email marketing statistics provided by ConstantComment.com. All records and documents on file with CSR.



Chip Scale Review

2014 Editorial Calendar

January • February

3D - Wafer-Level Packaging - MEMS

Columns	Technical Features	Trade Show /Conferences
Semiconductor Industry Forecast	Probe Technology Advances	<ul style="list-style-type: none"> • BiTS Workshop Mesa, AZ (March 9-12) • IMAPS Device Packaging (DPC) Fountain Hills, AZ (March 10-13)
Competitive Strategies and Tactics for the Packaging Industry	Probing μ -bumps for wide I/O 3D SICs	
Putting 2.5D in Perspective	MEMS Mobile Devices	
Bringing New Electronic Materials to Market	3D IC Stacking	
BGA Socket Systems for Test and Verification	Next-generation TSV Filling by Electroplating	

R&D Institute Profile

Ad Space Close Jan 21 - Ad Materials Deadline Jan 24

March • April

OSATS – Packaging & Assembly – 3D TSVs

OSATS Market Update	European Assembly and Test	<ul style="list-style-type: none"> • SEMICON China Shanghai China (March 18-20) • APEX Expo Las Vegas, NV (March 25-27)
IC Packaging Technologies & Trends How the OSATs Stack Up	3D TSV & Heterogeneous Integration	
High-density 2.5D Interposer Market Update	Dispensing Trends	
TSV Reliability Challenges	Glass as a Future Packaging Platform	
	Die & Flip-chip Bonding	
	Semiconductor Packaging Materials	
	Advancements in PoP Technology	

R&D Institute Profile

International Directory of IC Packaging Foundries

Ad Space Close Feb 11 - Materials Close Feb 14

May • June

Materials - Test & Burn-in Sockets - 3D IC Integration

Advanced Packaging Materials Market Update	3DIC & TSV Interconnects	<ul style="list-style-type: none"> • MEPTEC Symposium on Polymers Wilmington, DE (May 6-8) • MEMS Tech Symposium San Jose, CA (May 22) • ECTC Lake Buena Vista, FL (May 27-30) • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 6-11) • SEMICON West San Francisco, CA (July 8-10)
Standards Update	Enabling Technologies for 2.5D IC/ Si Integration	
Patents Update	3D Integration of SiP	
	High Performance Test Sockets	
	Bond Testing	
	Metrology Trends	
	TSV Interposers	
	Laser Ablation Technology	

Special Feature: R&D Institute Profile

Special Feature: Executive Profile & Perspective

Ad Space Close March 28 - Ad Materials Close April 2

For ad inquiries: ads@chipscalereview.com - For editorial inquiries editor@chipscalereview.com

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.
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Chip Scale Review

2014 Editorial Calendar

July • August

Copper Pillar Bumping - Dicing & Singulation - Assembly & Test

Columns	Technical Features	Trade Show /Conferences
Assembly & Test Market Update	Copper Pillar Bumping	<ul style="list-style-type: none"> • SEMICON Taiwan Taipei, Taiwan (Sept 3-5) • MEPTEC Medical Microelectronics Conference Portland, OR (Sept 18-19)
Burn in and Test Market Update	Scalable Approaches for 2.5D IC Assembly	
	Cost Reduction of MEMS	
	Bonding/De-Bonding/Wafer-thinning Handling	
	Dicing & Singulation	
	Spring Contact Probes in Wafer Test Applications	
	Solder Trends	

International Directory of Test and Burn-in Sockets

Ad Space Close May 30 - Ad Materials Close Jun 4

September • October

Thermocompression Bonding – Wafer Probing – Wire Bonding

Test Trends	TCB for 2.5D/3D Assembly	<ul style="list-style-type: none"> • SMTA International Rosemont, IL (Sept 28-Oct 2) • SEMICON Europa Grenoble, France (Oct 7-9) • IMAPS Microelectronics Symposium San Diego, CA (Oct 13-16) • T-Sensors Summit San Diego, CA (Oct 15-16) • International Test Conference (ITC) Seattle WA (Oct 21-24) • MEMS Executive Congress Scottsdale, AZ (Nov 5-7) • IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Nov 11 -13)
Patents	3D Packaging Through-glass Vias (TGV)	
	Wafer Probers & Probe Cards	
	High-reliability Wire Bonding	
	Cleaning Processes	
	Automotive Electronic Packaging	

International Directory of Bonding Equipment for 2.5D and 3D Assembly

Special Feature: Executive Profile & Perspective

Ad Space Close Aug 8 - Ad Materials Close Aug 13

November • December

3D TSVs – Package Test – Inspection

Advances in Burn-in & Test Sockets	Heterogeneous Integration Through-die Stacking	<ul style="list-style-type: none"> • MEPTEC Packaging, Assembly & Test Conf. Santa Clara, CA (Nov TBD) • SEMICON Japan Tokyo, Japan (Dec 3-5) • RTI 3D ASIP Conference Burlingame, CA (Dec 10-12) • SEMI European 3D TSV Summit Grenoble France (Jan 2015)
Green Electronics	3D TSVs	
MEMS Industry Report	HVM of 3D ICs	
	Solder Ball Placement	
	Reliable Flip-chip Interconnection	
	Package Inspection	
	Failure Analysis	

Ad Space Close Oct 10 - Materials Close Oct 15









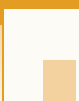
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ADVERTISING RATES & SPECIFICATIONS

ADVERTISING SPECIFICATIONS

2 PAGE SPREAD		
	Trim Size 15.75" x 10.875"	Bleed Size .125" beyond all sides
1 PAGE		
	Trim Size 7.875" x 10.875"	Bleed Size 8.125" x 11.125"
2/3 PAGE		
	Ad Size 4.5" x 10"	Bleed Size This type of ad does not bleed
1/2 PAGE ISLAND		
	Ad Size 4.5" x 7.375"	Bleed Size This type of ad does not bleed
1/2 PAGE HORIZONTAL		
	Ad Size 7" x 4.875"	Bleed Size This type of ad does not bleed
1/2 PAGE VERTICAL		
	Ad Size 3.375" x 10"	Bleed Size This type of ad does not bleed
1/3 PAGE HORIZONTAL		
	Ad Size 4.625" x 4.875"	Bleed Size This type of ad does not bleed
1/3 PAGE VERTICAL		
	Ad Size 2.1875" x 10"	Bleed Size This type of ad does not bleed
1/4 PAGE VERTICAL		
	Ad Size 3.5" x 4.875"	Bleed Size This type of ad does not bleed

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All Ads Must be Submitted to Correct Size

Please contact the *Chip Scale Review* Publisher or Sales Representative for mechanical requirements and specifications.

FULL COLOR ADVERTISING RATES

2 PAGE SPREAD (Bleed or Non-Bleed)		
1 – 2x \$7,020	3 – 4x \$6,545	5 – 6x \$6,240
1 PAGE (Bleed or Non-Bleed)		
1 – 2x \$4,500	3 – 4x \$4,200	5 – 6x \$3,800
2/3 PAGE		
1 – 2x \$3,690	3 – 4x \$3,385	5 – 6x \$3,170
1/2 PAGE ISLAND, HORIZONTAL or VERTICAL		
1 – 2x \$2,900	3 – 4x \$2,750	5 – 6x \$2,530
1/3 PAGE HORIZONTAL or VERTICAL		
1 – 2x \$2,470	3 – 4x \$2,335	5 – 6x \$2,145
1/4 PAGE VERTICAL		
1 – 2x \$2,160	3 – 4x \$2,025	5 – 6x \$1,855
COVER POSITIONS (Frequency discounts available)		
Inside Front Cover \$5,500	Inside Back Cover \$4,800	Outside Back Cover \$6,500

Rates are gross.

Ad placements that require special positioning or a guaranteed page or editorial placement are subject to a 10% premium fee in addition to the earn rate.

Rates are based on the total number of insertions of any size within the contract year. Rates are subject to a 15% advertising agency commission. Agency commission will be disallowed if payment has not been received at the Publisher's office by the 35th day following the invoice date. Ads cancelled after the materials close date will subject the advertiser to a 100% penalty at the Publisher's discretion.

GENERAL CONTRACT AND RATE POLICY

All advertising is accepted at the Publisher's discretion. The advertising insertion order is an official and legally binding contract between the advertiser and/or agency and *Chip Scale Review* magazine. Neither the advertiser nor agency may amend our advertising policies by notation to the insertion order, verbally or through any other document whether it is part of the insertion order or separate.

Rate & specifications are effective 12/01/2013

Advertising Rates and Specifications are subject to change without notice and are contingent on logistics and magazine production.

CSR Tech Monthly eNewsletter

CSR Tech Monthly brings the latest in technology features, key industry news, event coverage, and significant new product information right to your in-box. Ask your sales person about sponsoring dedicated special issues of CSRTM.

CSRTM RATE CARD

TOP BANNER (625 x 80)			
1x	3x	6x	12x
\$1025	\$925	\$850	\$775
SMALL BANNER (485 x 90)			
1x	3x	6x	12x
\$775	\$700	\$625	\$550
SKYSCRAPER (120 x 240)			
1x	3x	6x	12x
\$775	\$700	\$625	\$550
TEXT/TILE (120 x 120)			
1x	3x	6x	12x
\$625	\$575	\$525	\$475

Measurements are in pixels

CSRTM CALENDAR

ISSUE	BROADCAST	SPACE CLOSE	MATERIALS CLOSE
JANUARY	January 21	January 14	January 17
FEBRUARY	February 18	February 11	February 14
MARCH	March 18	March 11	March 14
APRIL	April 15	April 8	April 11
MAY	May 20	May 13	May 16
JUNE	June 17	June 10	June 13
JULY	July 15	July 8	July 11
AUGUST	August 19	August 12	August 15
SEPTEMBER	September 16	September 9	September 12
OCTOBER	October 21	October 14	October 17
NOVEMBER	November 18	November 11	November 14
DECEMBER	December 16	December 9	December 12



CSR Tech Monthly

Chip Scale Review Website

Chipscalereview.com Web Traffic*
October 2012 - October 2013

* source: 3rd party data analytical services

CSRTM AD SPACE FILE SPECIFICATIONS

Material Format: gif, jpg, png or swf
Max. Animation Time: 30 sec., 3 loops max
Max. File Size: 35Kb
Supply the click through url with your material



Chip Scale Review TEAM OF EXPERTS

The editors, writers, and contributors who provide our editorial are industry experts with real time experience in semiconductor packaging, engineering, design and test.

KIM NEWMAN, Publisher, A 14 year veteran at CSR, she joined the magazine's sales and marketing team in 1999. Kim assumed the Publisher role in 2007 and manages the public relations strategy and execution of programs for semiconductor packaging sector industry firms. Her overall responsibilities includes publication of all CSR generated media, oversight of technical content generation for contributed editorial and development of client and agency projects including marketing collateral in support of sustaining positive client relationships. Additional and significant efforts are channeled to industry trade shows and industry events and are evidenced by the success of the International Wafer-level Packaging Conference (IWLPAC) with additional acknowledgements by the leading trade venues. She is synonymous with the packaging industry. Her previous positions include sales operations management at Memorex Corporation. Kim graduated with a BS from the University of California at Davis.

LAWRENCE MICHAELS, Managing Director, became associated with Chip Scale Review initially as a business and operations advisor in 2008 and joined fulltime in 2012. He brings with him a 20+ years of experience in senior systems engineering and a technical program management background from the Enterprise Business System and software industry. Additionally, he has held significant manufacturing and management positions in the avionics & aerospace industry. Lawrence holds a BS from University of Colorado and an MBA from California Lutheran University.

DEBRA VOGLER, Sr. Technical Editor, joined the CSR team in 2012. She is responsible for technical content selection, author coordination, editing and editorial Advisory Board representation. Having served as the Sr. Technical Editor for Solid State Technology in excess of 10 years, Debra is well-known in the advanced packaging community as a technical editor, industry media commentator covering symposiums and conferences. Debra holds a graduate degree in physics from Marquette University.

RONALD J. MOLNAR is an industry veteran who has enjoyed a distinguished career in the fields of Optoelectronics, ASIC, Bipolar Logic & Memory, Contract IC Assembly, Package Design and Test, Equipment Automation, Sales Representation, and consulting. He's held VP of Engineering positions with Amkor Technology, Abpac, and Tinos. He is currently Executive Director of Az Tech Direct, LLC. University of California, Berkeley BSEE, Semiconductor Physics.

THOMAS H. Di STEFANO, Ph.D. was the founding president of Tessera Technologies and helped build Tessera into a world leader in miniaturized packaging. Royalties from U.S. Patents coauthored by Di Stefano produced well above \$1Billion revenue for Tessera. In 2011, SEMI names Thomas Di Stefano as one of the recipients of the SEMI Award for North America for contributions to the development and commercialization of Micro Ball Grid Array (μ BGA) technology. Tom is also a co-founder of Chip Scale Review.

JASON MIRABITO, Contributing Editor on Patent Legislation, is a member of the Mintz, Levin, Cohn, Ferris, Glovsky and Popeo Law Firm and is contributing editor of the Patents column. LLM, Georgetown Law Center Juris Doctor, American University BSEE, Engineering Physics : New York University

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